

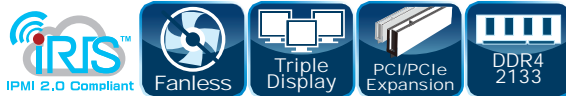
# TANK-871-Q170

- High-Performance 6th Generation Intel® Core™ Processor
- Fanless Embedded Computer



## Features

- 6th Gen Intel® Core™ processor platform with Intel® Q170 chipset and DDR4 memory
- Triple independent display with high resolution support
- Rich high-speed I/O interfaces on one side for easy installation
- IEI iRIS-2400 solution

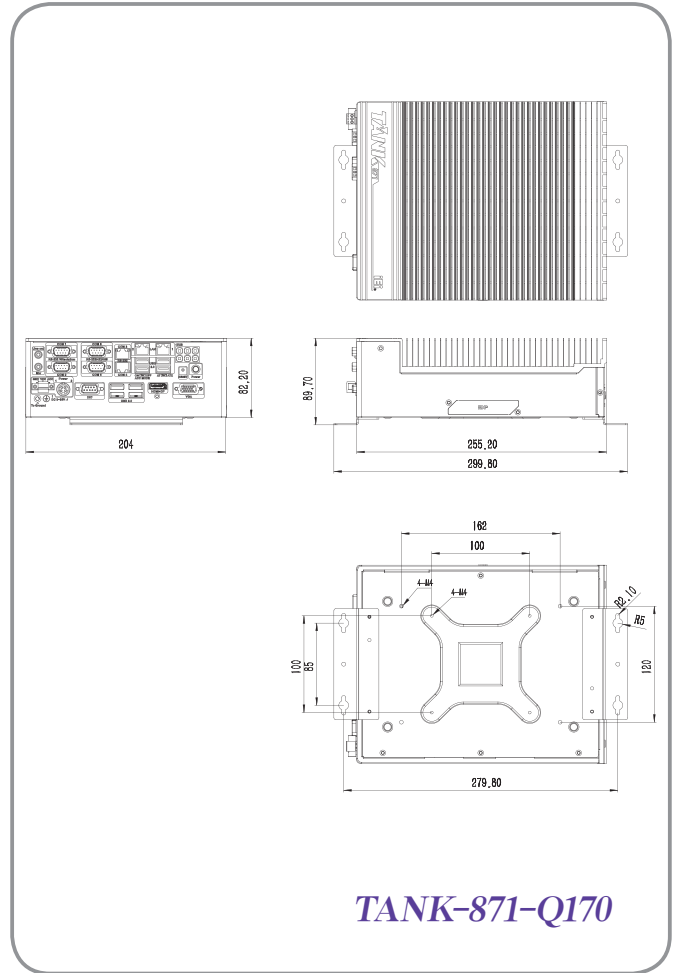
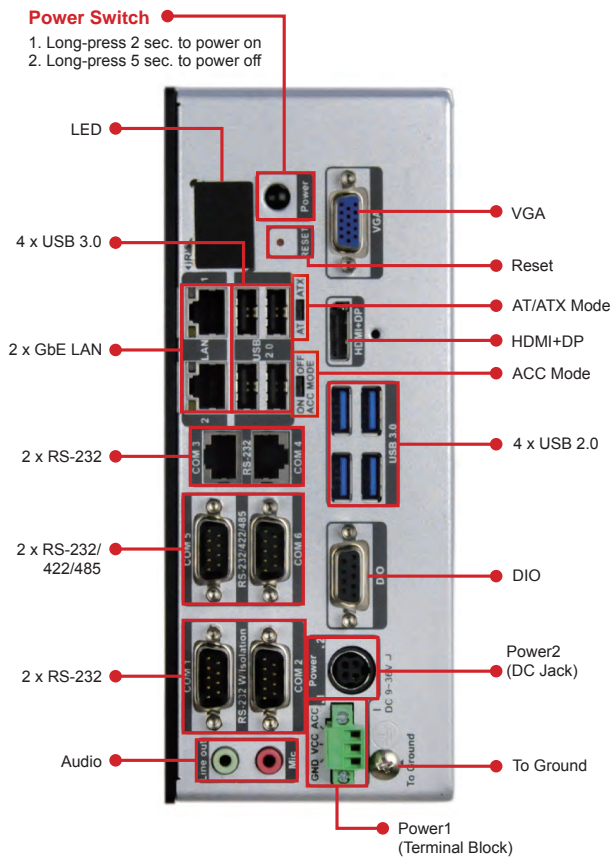


## Specifications

Model Name		TANK-871-Q170
Chassis	Color	Black C + Silver
	Dimensions (WxDxH) (mm)	82.2 x 255.2 x 204
	System Fan	Fanless
	Chassis Construction	Extruded aluminum alloy
Motherboard	CPU	Intel® Core™ i7-6700TE 2.4 GHz Intel® Core™ i5-6500TE 2.3 GHz
	Chipset	Intel® Q170
	System Memory	2 x 260-pin DDR4 SO-DIMM, pre-installed one 4GB (system max: 64GB)
IPMI	iRIS solution	1 x iRIS-2400 (optional)
Storage	Hard Drive	2 x 2.5" SATA 6Gb/s HDD/SSD bay (RAID 0/1 support)
I/O Interfaces	USB 3.0	4
	USB 2.0	4
	Ethernet	2 x RJ-45 LAN1 (iRIS): Intel® I210 PCIe controller LAN2: Intel® I219LM PCIe controller
	COM Port	4 on rear I/O (2 isolation) 2 on rear I/O
	Digital I/O	8 bit Digital I/O, 4 bit input / 4 bit output
	Display	1 x VGA, 1 x HDMI+DP, 1 x IDP
	Resolution	VGA: Up to 1920 x 1200@60Hz HDMI: Up to 4096 x 2160@24Hz
	Audio	1 x Line-out ; 1 x Mic-in
	Wireless	1 x 802.11a/b/g/n/ac (optional)
Expansions	PCIe Mini	1 x Half-size PCIe Mini slot 1 x Full-size PCIe Mini slot (supports mSATA, colay with SATA)
Power	Power Input	DC Jack: 9 V~36 V DC Terminal Block: 9 V~36 V DC
	Power Consumption	19 V@3.68 A (Intel® Core™ i7-6700TE with 8 GB memory)
Reliability	Mounting	Wall mount
	Operating Temperature/Humidity	i7-6700TE: -20°C ~ 45°C with air flow (SSD), 10% ~ 95%, non-condensing i5-6500TE: -20°C ~ 60°C with air flow (SSD), 10% ~ 95%, non-condensing
	Storage Temperature/Humidity	*-40°C ~85°C with air flow (SSD), 10% ~ 90%, non-condensing
	Operating Shock	Half-sine wave shock 5G; 11ms; 100 shocks per axis
	Operating Vibration	MIL-STD-810G 514.6 C-1 (with SSD)
	Weight (Net/Gross)	TBD
	Safety/EMC	CE/FCC
OS	Supported OS	Microsoft® Windows® 8 Embedded, Microsoft® Windows® Embedded Standard 7 E

Fully Integrated I/O

Dimensions (Unit: mm)



TANK-871-Q170

Ordering Information

Part No.	Description
TANK-871-Q170i-i7/4G-R10	Ruggedized fanless embedded system with Intel® Core™ i7-6700TE 2.4 GHz (up to 3.4 GHz, quad core, TDP 35W), 4GB DDR4 pre-installed memory, VGA/HDMI+DP/iDP, iRIS-2400 optional, 9~36V DC, RoHS
TANK-871-Q170i-i5/4G-R10	Ruggedized fanless embedded system with Intel® Core™ i5-6500TE 2.3 GHz (up to 3.3 GHz, quad core, TDP 35W), 4GB DDR4 pre-installed memory, VGA/HDMI+DP/iDP, iRIS-2400 optional, 9~36V DC, RoHS

Options

Part No.	Description
19200-000605-00-RS	Fan, +12V DC, 4-pin, 40 mm x 40 mm x10 mm, 6500RPM, RoHS
32702-000400-200-RS	European power cord
63040-010090-101-RS	Adapter power, FSP090-DIEBN2, 9NA0904739, Active PFC, Vin:90~264VAC, 90W, plug=6.5mm, cable=1500mm, Erp (no load 0.5W), Vout:19VDC, 4-pin DIN with lock, CCL, RoHS
iRIS-2400-R10	IPMI 2.0 adapter card with AST2400 BMC chip for DDR3 SO-DIMM socket interface
DP-DP-R10	DisplayPort to DisplayPort converter board (for IEI IDP connector)
DP-HDMI-R10	DisplayPort to HDMI converter board (for IEI IDP connector)
DP-LVDS-R10	DisplayPort to 24-bit dual channel LVDS converter board (for IEI IDP connector)
DP-VGA-R10	DisplayPort to VGA converter board (for IEI IDP connector)
DP-DVI-R10	DisplayPort to DVI-D converter board (for IEI IDP connector)
TANK-870-Q170-WES7E64-R10	OS Image with Windows® Embedded Standard 7 E 64-bit for TANK-870-Q170 Series, with DVD-ROM, RoHS

Packing List

1 x Utility CD	1 x Chassis Screw	1 x One Key Recovery CD	1 x Mounting Bracket
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